

# TECHNICAL DATA SHEET

## SnPb60 SOLDER STICKS

### PRODUCT DESCRIPTION

PAI SnPb60 Sticks are being formulated with High Virgin Raw Metals Processed in state-of-the-art Vacuum Technology that brings world class Quality along. Here, Oxygen interaction with Alloy is Nil and thus, Dross formation is reduced at PCB Assembly Process. Also an increase flow rate & reduced impurities found. PAI SnPb60 Alloy is compatible for a typical range of Flux Application Formulas used in Electronics Industry Today.

### STORAGE AND HANDLING

- Do not use Fire near storage area.
- Store in Dry, Cool and Non-Corrosive environment.
- Wear Personal Protective Equipments while Handling.
- Wear Personal Protective Equipments while Processing.

### ALLOY COMPOSITION

SI No	Metal	Sn40Pb60 Solder Sticks	ISO9453 Specification
1	Sn	39.5% - 40.50%	39.5% - 40.50%
2	Pb	Rem	Rem
3	Sb	<0.50%	0.50%
4	Bi	<0.25%	0.25%
5	Cd	<0.005%	0.005%
6	Cu	<0.08%	0.08%
7	Au	<0.05%	0.05%
8	In	<0.10%	0.10%
9	Ag	<0.10%	0.10%
10	Al	<0.001%	0.001%
11	As	<0.03%	0.03%
12	Fe	<0.02%	0.02%
13	Ni	<0.01	0.01
14	Zn	<0.001	0.001

### PHYSICAL CHARACTERISTICS OF APPLICATION

Alloy	Sn40/Pb60
Shape	Rectangular Form
Density	8.4gm/cm <sup>3</sup> at 20 <sup>0</sup> C
Solidus, Liquidus	183 <sup>0</sup> C, 238 <sup>0</sup> C
Package Form	25Kgs
Application	Wave Soldering / HASL Process
Standards Considered	JIS-Z-3282
Shelf Life	10 Years

### TECHNICAL SPECIFICATIONS

<b>Technical Factors Recommended</b>	<b>Specifications</b>
Solder Pot Temperature	250°C to 260°C
Dwell Time	2 Sec to 4 Sec
Immersion	0.5% to 0.70% of PWBs Thickness that being Processed
Dross Recovery	Once in Every 8 Hours
Impurities Level Check	In-House Specifications
Other Factors	Refer Liquid Flux Manufacturer Specifications for desired Yields

**Note:** The recommendations stated above have been contributed for desired Solder Joints and shall modify if required based on the end user Specifications.